HYPERKINETIC™ CONNECTORS

HKC (cPCI SERIES)

HKX (VPX COMPATIBLE SERIES)

...FOR SUPERIOR PERFORMANCE IN ALL APPLICATIONS

ISO 9001

www.iehcorp.com
CONTENTS
HKC & HKX CONNECTORS

PAGE

3    Introduction
4-5  cPCI Specifications
6    HKC Ordering Chart

HKC SERIES

7    Daughter Card Type “A”
8    BackPlane Type “A”
9    Daughter Card Type “B”
10   BackPlane Type “B”
11   Daughter Card Type “AB”
12   BackPlane Type “AB”
13   Keying & Code Layout
14   NASA Goddard Part Numbers
15   HKC Accessories

16-17 VPX Specifications
18   HKX Ordering Chart

HKX SERIES

19   Plug-In Module Wafer to Backplane Pin Mapping
20   P0 & P1, Daughter Card Connector Dimensions
21   P0 & P1, Backplane Connector Dimensions
22   3U Configuration With Shell, Daughter Card & Backplane Connector Dimensions
23   Polarization Chart
The HYPERBOLOID contact is an advanced design that satisfies performance requirements previously considered impossible. Radically different in concept, it is used in connectors having the highest standards of performance. The distinguishing feature of the HYPERBOLOID socket is the hyper-boloid-shaped sleeve formed by straight wires strung at an angle to the longitudinal axis. Viewed from the side, you see a curve defined by a series of apparent short straight line segments which are tangent lines to points along a hyperbolic curve. This geometry provides for a design which has a decreasing circumscribed circle when viewed from the entry. It begins larger than the pin acceptance diameter and is less than this same diameter at the center. When the pin is inserted into this sleeve, the wires stretch, well within elastic limits, to accommodate it. In so doing, the wires wrap themselves around the pin providing a number of continuous line contact paths. The illustration below will assist in visualization.

The actual physical construction of the contact involves several components. The wires are strung on an internal wire carrier (inner sleeve) which is subsequently capped or enclosed by a front outer ring (front sleeve) and rear ring which includes the termination configuration (terminal). All components to the assembly are completely finished with the specified electroplating prior to assembly. The wires are continuous process plated on reel before use. In this manner, interface finish requirements can be controlled very closely without the common problems of gradient, shadow, or other finish imperfections often appearing in alternative designs. Very often, this processing feature permits the specifier to reduce precious metal content with resultant savings. Joints are calculated interference fits, insuring gas tight interfaces between all elements of the HYPERBOLOID construction. An exploded view is provided next.

The unique geometry, precision processing, and careful attention to quality result in a highly desirable contact design which provides:

- **VLIF (Very Low Insertion Force):** Common sizes #22 and less average under one ounce per contact.
- **Extraordinary Resistance to Shock & Vibration:** Tests exceeding 300 g’s without discontinuity.
- **Duty Cycle Exceeding 100,000 Mate/Demate:** The burnishing action of the wires on the pin surface is non-destructive. Unlike the “plow” and scrape action of common designs, HYPERBOLOID’s gentle mating action enhances life.
- **Low, Low Contact Resistance:** The multiplicity of line contact, as opposed to point contact in other designs, provides an excellent interface exhibiting low contact resistance (often less than 1/2 of MIL spec. allowances). This characteristic also provides for a cooler running contact under load.
- **Improved Current Carrying Capacity:** The low contact resistance gives a lower °C rise from ambient under load. This feature often allows the user to operate the same size contact under higher load.
- **Highest Reliability:** In use for over 40 years under the most demanding conditions HYPERBOLOID has proven itself to be the leading design for integrity and reliability. On space platforms, ships and boats at sea, land vehicles, fighter and transport aircraft, missiles, torpedoes, medical and transplant electronics, industrial and environmental controls, rail, construction, ATE and test equipment, PGA sockets, test interface stations, and other applications, HYPERBOLOID has lived up to its promise of the highest reliability connector available.
FEATURES & BENEFITS

Interchangeable with the board layout on COTS System
High Reliability Hyperboloid Contact System
Standard 2mm Footprint of cPCI PICMG 2.0
LCP Insulator meets NASA Outgassing Requirements
Contact identification in accordance with IEC 61076-4-101:2001
Press-fit termination available, see ordering chart

PRELIMINARY SPECIFICATIONS
(See online catalog for latest info)

GENERAL:
Design Criteria: IEC 61076-4-101:2001
Contact Spacing: 2.00mm square
Maximum Allowable Gap Between Mating Connectors: 0.050 [1.27]

MATERIALS
Pin Contacts: Beryllium Copper Pin Contacts:
BeCu per ASTM B196/B196M-07, C17200
Socket Contacts: Beryllium Copper Hyperboloid Socket Wires and Brass Body:
BeCu per ASTM B197/B197M-07, C17200
Insulator: 30% Glass filled LCP (meets NASA outgassing specification):
LCP0120G30A43430 IAW ASTM-D5138
Mating Surface, Finishes: 30 µin or 50 µin min. Gold / 50 µin min. Nickel:
Gold per MIL-DTL-45204 Type II, Class 0.75 or 1.27 min, Code C over Nickel,
0.000050 min., per SAE AMS-QQ-N-290 over Copper per SAE AMS 2418
Termination Solder Dip: Gold per MIL-DTL-45204 Type II, Class 0.25 or 0.75 min, Code C over Nickel,
0.000050 min., per SAE AMS-QQ-N-290 over Copper per SAE AMS 2418 or
Solder Dip over Nickel, 0.000050 min., per SAE AMS-QQ-N-290 over Copper per SAE
AMS 2418
Terminiation Press-In: Gold per MIL-DTL-45204 , Class 1.27 min, , Grade C over Nickel, 0.000050 min., per
SAE AMS-QQ-N-290 over Copper per SAE AMS 2418 or Tin/Lead per SAE-AMS-P-81728

PERFORMANCE:
Contact Current Rating: 2 Amp Max per Contact (higher ratings may be supported-contact factory)
Insulation Resistance: >5000 megaohm
Flammability Rating: 94 V-O
Temperature: -55°C to +125°C (-67°F to +257°F)
Mating Force: [16.38] LBF average (per mated connector pair for both 95 and 110 Signal Contacts)
De-mating Force: [13.2] LBF average (per mated connector pair for both 95 and 110 Signal Contacts)
Contact Life (Mate/Demate): [>5000] Cycles (per mated connector pair)
Contact Resistance: 4.85 milliohms average
Low Level Contact Resistance: 7.20 milliohms average
Dielectric Withstanding Voltage:1000V RMS
Humidity: IAW EIA-364-31, Method IV, except 7A & 7B (not required)
Vibration: IAW EIA-364-28 & MIL-DTL-55302 (par. 4.5.10)
Shock: IAW EIA-364-27 & MIL-DTL-55302 (par. 4.5.14)
Salt Spray: IAW EIA-364-26 & MIL-DTL-55302 (par. 4.5.11)
Temperature Cycling: IAW EIA-364-32 & MIL-DTL-55302 (par. 4.5.13)
Weight: P1/P4: 0.23 oz.; P2/P5: 0.20 oz.; P3: 0.18 oz.;
J1/J4: 0.68 oz.; J2/J5: 0.64 oz.; J3: 0.55 oz.
cPCI SERIES (2mm) CONNECTOR

HKC SERIES

Type “A” Style

2mm Connector Mated Pair

Type “B” Style

Type “AB” Style

<table>
<thead>
<tr>
<th>General Specification</th>
<th>311P Series = NASA GSFC S-311-P-822</th>
</tr>
</thead>
<tbody>
<tr>
<td>3U/6U Form Factor</td>
<td>P1/P4</td>
</tr>
<tr>
<td>Part Number Reference</td>
<td>HKC110BCA</td>
</tr>
<tr>
<td>Location/Contact Gender</td>
<td>Backplane/Male Pin</td>
</tr>
<tr>
<td>Number of Contacts</td>
<td>110 signal total 22 ground</td>
</tr>
</tbody>
</table>

140 58th Street 8E, Brooklyn, NY 11220    Ph: (718) 492-4448  Fax: (718) 492-9898    www.iehcorp.com
Please contact the factory or your IEH representative for price and delivery information
NOTE:
Recommended PCB Metrics
Solder
   Diameter of Drilled Hole:  Ø0.9mm ±0.02mm
   Diameter of Finished Plated-through Hole:  Ø0.8mm ±0.05mm
Compliant
   Diameter of Drilled Hole:  Ø0.7mm ±0.02mm
   Diameter of Finished Plated-through Hole:  Ø0.6mm ±0.05mm
NOTE:
Recommended PCB Metrics
Solder
  Diameter of Drilled Hole:
  Ø0.8mm ±0.02mm
  Diameter of Finished Plated-through Hole:
  Ø0.7mm ±0.05mm
Compliant
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  Diameter of Finished Plated-through Hole:
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Compliant
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Diameter of Finished Plated-through Hole:
Ø0.6mm ± 0.05mm

<table>
<thead>
<tr>
<th>SIZE</th>
<th>A</th>
<th>B</th>
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<tbody>
<tr>
<td>095</td>
<td>1.495 [37.98]</td>
<td>1.417 [36.00]</td>
</tr>
<tr>
<td>110</td>
<td>1.731 [43.98]</td>
<td>1.654 [42.00]</td>
</tr>
</tbody>
</table>
BACKPLANE, TYPE “B”  
HKC[095,110]BCB

PCB LAYOUT

NOTE:
Recommended PCB Metrics  
Solder
Diameter of Drilled Hole:  
Ø0.8mm ±0.02mm  
Diameter of Finished Plated-through Hole:  
Ø0.7mm ±0.05mm
Compliant
Diameter of Drilled Hole:  
Ø0.8mm ±0.02mm  
Diameter of Finished Plated-through Hole:  
Ø0.7mm ±0.05mm

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<td>1.654 [42.00]</td>
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</table>
NOTE:
Recommended PCB Metrics
Solder
  Diameter of Drilled Hole: Ø0.9mm ± 0.02mm
  Diameter of Finished Plated-through Hole: Ø0.8mm ± 0.05mm
Compliant
  Diameter of Drilled Hole: Ø0.7mm ± 0.02mm
  Diameter of Finished Plated-through Hole: Ø0.6mm ± 0.05mm

<table>
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<td>1.654 [42.00]</td>
</tr>
</tbody>
</table>
NOTE:

Solder

Diameter of Drilled Hole: 
Ø0.8mm ± 0.02mm

Diameter of Finished Plated-through Hole: 
Ø0.7mm ± 0.05mm

Compliant

Diameter of Drilled Hole: 
Ø0.8mm ± 0.02mm

Diameter of Finished Plated-through Hole: 
Ø0.7mm ± 0.05mm

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</tr>
<tr>
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<td>1.731</td>
<td>1.654</td>
</tr>
</tbody>
</table>
KEYING & CODE LAYOUT

BACKPLANE KEY

Example diagram for key code 3456

Example diagram for key code 2348

*Color Keying Not Available
**In Stock (Other keys for special order)

1567**
3456**
1235
1256
1258
1578
2345
2347
2356
2358
2368
2456
2467
2468
2567
2678
3457
3568
3578
4567
4568
1278**
2348**
1234
1236
1237
1238
1246
1247
1268
1345
1348
1357
1358
1378
1457
1467
1478
1568
1678
2346
3467
3478
NASA GODDARD PART NUMBERS

<table>
<thead>
<tr>
<th>Goddard Designator</th>
<th>Connector Gender Designation</th>
<th># of Contacts</th>
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<tbody>
<tr>
<td>311P822</td>
<td>Male Connector</td>
<td>110 Signal Contacts</td>
</tr>
<tr>
<td>MC</td>
<td>Female Connector</td>
<td>095 Signal Contacts</td>
</tr>
<tr>
<td>110</td>
<td>Male Adaptor</td>
<td></td>
</tr>
<tr>
<td>A</td>
<td>Female Adaptor</td>
<td></td>
</tr>
<tr>
<td>S</td>
<td>Female to Female Adaptor</td>
<td></td>
</tr>
<tr>
<td>D4</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Solder Tail-Length**

<table>
<thead>
<tr>
<th>Designation</th>
<th>Backplane Connector Tail Length</th>
<th>Daughter Card Connector Tail Length</th>
</tr>
</thead>
<tbody>
<tr>
<td>D</td>
<td>.216&quot; [5.50]</td>
<td>.123&quot; [3.12]</td>
</tr>
<tr>
<td>D1</td>
<td>.380 [9.65]</td>
<td>TBD</td>
</tr>
<tr>
<td>D2</td>
<td>.630&quot; [16.00]</td>
<td>TBD</td>
</tr>
<tr>
<td>D3</td>
<td>TBD</td>
<td>TBD</td>
</tr>
<tr>
<td>D4</td>
<td>.166&quot; [4.22]</td>
<td>.166&quot; [4.22]</td>
</tr>
<tr>
<td>D5</td>
<td>.265 [6.73]</td>
<td>TBD</td>
</tr>
</tbody>
</table>

**Solder Tail Finish**

- G: Gold flash over nickel
- S: 63/67 Tin/Lead Solder over Nickel

**Connector Style**

- A: With multi-purpose center
- B: Without MPC

CROSS REFERENCE — IEH PART NUMBERS TO NASA GODDARD

<table>
<thead>
<tr>
<th>IEH</th>
<th>NASA</th>
</tr>
</thead>
<tbody>
<tr>
<td>HKC095DCB</td>
<td>311P822MC095B</td>
</tr>
<tr>
<td>HKC110DCB</td>
<td>311P822MC110B</td>
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<tr>
<td>HKC095BCB</td>
<td>311P822FC095B</td>
</tr>
<tr>
<td>HKC110BCB</td>
<td>311P822FC110B</td>
</tr>
</tbody>
</table>
ACCESSORIES

Key Insertion Tool & Pin Carrier

Key Insertion Tool

For Type “A” P/N: B1430-61

Pin Carrier: To be used as an aid for Soldering and Press-in Compliant

For HKC110BCA

For HKC[095,110]BCB & HKC[095,110]BCAB

*Delivered assembled to every connector.

<table>
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<tr>
<td>110</td>
<td>1.731 [43.98]</td>
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</table>
VITA VPX Compatible Hi-Speed, High-Density Hyperboloid Modular Interconnects

The HKX is a shielded, high-density, hi-speed modular interconnect which employs the mission critical capabilities of the hyperboloid contact.

IEH developed the HKX interconnect platform to meet or exceed future high-level requirements for applications such as -- avionics, radar, weapon systems, data storage, and communications including video.

Offering both VITA VPX and custom platforms.

Primary advantages:

• The original, proven hyperboloid contact system
• High-level vibration and mechanical shock protection
• Resistant to Fretting
• Modular construction allows for either VITA VPX footprint or for custom configurations
• Data rates up to 10 Gbps while retaining the same VITA 46 platform
• High quality materials meets the most demanding applications and specifications
• Very low insertion and extraction forces
• Custom wafer design allows for mixing differential and single-ended circuits

Key Features of HKX

• Fully compatible pwb footprint with VITA 46 standard
• Hi-Speed: the HKX is designed for 10 Gbps data rate performance
• 100 ohm impedance for differential pair configuration
• The daughtercard assembly is optimized for differential pair architecture on a 1.8mm by 1.35mm grid
• The daughtercard connector contains wafers, which provide differential, single-ended and power options
• LCP housings meets NASA outgassing requirements
• ESD protection supports 2-level maintenance designs
• Available with either solder-dip or compliant terminations
HKX Electrical Specifications
- Data Rate: Up to 10 Gbps
- Differential Impedance: 100 ohms
- Differential Insertion Loss: -9 dB up to 10 GHz (20 Gbps)
- Far End Crosstalk: -34 dB up to 5 GHz
- Near End Crosstalk: -32 dB up to 5 GHz
- Signal Contacts: 2 amp
- Power Wafer: 12 amps per wafer at 30°C T-Rise
- Compliance Pin to Plated Through Hole Resistance: 1 milliohm max
- Dielectric Withstanding Voltage: 500 volts RMS
- Insulation Resistance: 1000 megaohms

HKX Mechanical Specifications
- Signal and Ground Contact:
  - Insertion force per contact: 1.6 oz max, 0.9 oz typical
  - Extraction force per contact: 1.2 oz max, 0.7 oz typical
  - Durability: 500 cycle minimum
- Number of contacts: 9 per wafer
- Number of wafers: 40 for 3U; CU - custom configuration upon request.
- Contact resistance: <8 milliohms per contact
- Wafer pitch: 1.8 mm
- Slot pitch: 20.30 mm

HKX Environmental Specifications
- Temperature: -55°C to 125°C
- Temperature Life: 1000 hours at 125°C

Printed Circuit Board Specifications
- Minimum Backplane and Daughter Card Thickness: 2.36 mm and 1.53 mm
- Daughter Card pattern finished hole size: 0.56 +/- 0.05 mm
- Backplane pattern finished hole size: 0.56 +/- 0.05 mm
- Backplane hole pattern: 1.8 mm X 1.8 mm (9-holes per row)
- Daughter card hole pattern: 1.8 mm X 1.35 mm (7-holes per row)

HKX Materials and Finishes
Backplane, Signal and Ground Contacts:
- Brass per ASTM B16 /B16M-10, C36000
- Gold per MIL-DTL-45204 Type II, Class 1.27, Code C over Nickel, 0.000050 min., per SAE AMS QQ-N-290 over Copper per SAE AMS 2418

Socket Contacts:
- Brass per ASTM B16 /B16M-10, C36000
- Contact wires - Gold per MIL-DTL-45204 Type II, Class 1.27, Code C over Nickel, 0.000050 min., per SAE AMS QQ-N-290 over Copper per SAE AMS 2418
- All else - Gold per MIL-DTL-45204 Type II, Class .75, Code C over Nickel, 0.000050 min., per SAE AMS QQ-N-290 over Copper per SAE AMS 2418

Differential, Power, and Single-ended Daughter Card Wafer Groundplanes:
- Brass per ASTM B16 /B16M-10, C36000
- Gold per MIL-DTL-45204 Type II, Class 0.50, Code C over Nickel, 0.000050 min., per SAE AMS QQ-N-290 over Copper per SAE AMS 2418

Backplane Insulators and Daughter Card Wafer Insert Mold Material: LCP 30% Glass Filled
Backplane Guide Pin and Hardware: CRES 300 series PER ASTM A582/A582M
Daughter Card Connector Header, Keying Components and Hardware: CRES 300 series PER ASTM A582/A582M
HKX SERIES

ORDERING CHART

VITA Footprint

<table>
<thead>
<tr>
<th>Series</th>
<th>P0</th>
<th>P1</th>
<th>3U</th>
<th>3US</th>
<th>6U</th>
<th>CU</th>
</tr>
</thead>
<tbody>
<tr>
<td>3 Power Wafers</td>
<td>16 Differential Wafers</td>
<td>1 P0 &amp; 2 P1s</td>
<td>3U with CRES Shell</td>
<td>1 P0 &amp; 6 P1s</td>
<td>Custom</td>
<td></td>
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</tbody>
</table>

Hardware Type

<table>
<thead>
<tr>
<th>Hardware Type</th>
<th>GP</th>
<th>GS</th>
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<tbody>
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<td>Guide Pin</td>
<td>Guide Socket</td>
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Hardware Style

<table>
<thead>
<tr>
<th>Variation Code - Factory Assigned</th>
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<tbody>
<tr>
<td>A</td>
</tr>
<tr>
<td>B</td>
</tr>
<tr>
<td>0</td>
</tr>
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Termination Length - “L”

<table>
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<tr>
<th>Code</th>
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<tbody>
<tr>
<td>1</td>
<td>.109 [2.77]</td>
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<tr>
<td>2</td>
<td>.140 [3.56]</td>
</tr>
<tr>
<td>3</td>
<td>.172 [4.37]</td>
</tr>
<tr>
<td>4</td>
<td>.234 [5.94]</td>
</tr>
<tr>
<td>9</td>
<td>User Defined</td>
</tr>
<tr>
<td>0</td>
<td>Compliant</td>
</tr>
</tbody>
</table>

GUIDE HARDWARE ORDERING CHART

Please contact the factory or your IEH representative for price and delivery information

All information contained herein is believed to be reliable as of the date of publication, but is subject to change without notice. Current product drawings and specifications are available upon request from IEH.

IEH warrants its products to be free of defects affecting normal use. If any shipment is found to be defective we will accept return for repair or replacement at our option within one year of shipment. IEH is not responsible for incidental or consequential damages arising out of the use of our products.
HKX SERIES

PLUG-IN MODULE WAFER TO BACKPLANE PIN MAPPING

ODD DIFFERENTIAL PLUG IN MODULE
Daughter Card Mating Face

![Diagram of odd differential plug in module]

Daughter Card Row

<table>
<thead>
<tr>
<th>Daughter Card Row</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
</tr>
<tr>
<td>---</td>
</tr>
<tr>
<td>Pair 1</td>
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</tbody>
</table>

Daughter Card Row PCB Face

EVEN DIFFERENTIAL PLUG IN MODULE

![Diagram of even differential plug in module]

Daughter Card Row

<table>
<thead>
<tr>
<th>Daughter Card Row</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
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<tr>
<td>---</td>
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<tr>
<td>GND</td>
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SINGLE-ENDED PLUG IN MODULE

![Diagram of single-ended plug in module]

Daughter Card Row

<table>
<thead>
<tr>
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<tbody>
<tr>
<td>A</td>
</tr>
<tr>
<td>---</td>
</tr>
<tr>
<td>Sig 1</td>
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POWER PLUG IN MODULE

![Diagram of power plug in module]

Daughter Card Row

<table>
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</thead>
<tbody>
<tr>
<td>A</td>
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<tr>
<td>---</td>
</tr>
<tr>
<td>Power 1</td>
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**HKX SERIES**

**P0 & P1**

**DAUGHTERCARD CONNECTOR DIMENSIONS**

<table>
<thead>
<tr>
<th>CONNECTOR</th>
<th>A [mm]</th>
<th>B [mm]</th>
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<tbody>
<tr>
<td>P0</td>
<td>0.567</td>
<td>0.496</td>
</tr>
<tr>
<td>P1</td>
<td>1.134</td>
<td>1.063</td>
</tr>
</tbody>
</table>
HKX SERIES

P0 & P1
BACKPLANE CONNECTOR DIMENSIONS

CONNECTOR | A [mm] | B [mm]
---|---|---
P0 | .564 [14.33] | .496 [12.60]
P1 | 1.131 [28.73] | 1.063 [27.00]
3U CONFIGURATION WITH SHELL
DAUGHTERCARD & BACKPLANE CONNECTOR DIMENSIONS

*Dimensions are in millimeters
Polarization Chart

Use for Hardware Style: B

P0 & P1 Configuration

0°  45°  90°  270°  315°

1  2  3  4  5

3US Configuration with Shell

Pin Carrier: To be used as an aid for Soldering and Press-in Compliant

*Delivered assembled to every connector.
Listening to our customers and meeting their needs while continuously improving our processes and services.